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ABSTRACT

A semiconductor device comprising a semiconductor chip having an active and a passive surface, the passive surface adhesively attached to a substrate film by means of a multilayer composite; this composite comprising a metal foil having first and second surfaces and an adhesive layer attached on each of these surfaces. The multilayer composite has an average modulus larger than the modulus of the encapsulating molding compound used in the semiconductor device. By applying the composite to assembling face-up chip-scale devices, stress in solder joints is reduced and solder fatigue life enhanced.

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